

IFW



INT-03-008

May 21, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/807,036 03/23/04 |
Thomas Aisenbrey
LOW COST THERMAL MANAGEMENT DEVICE
OR HEAT SINK USING CONDUCTIVE
PLASTICS OR CONDUCTIVE COMPOSITES
| _____ |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

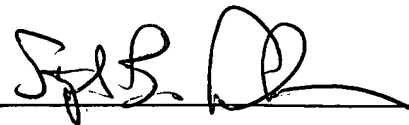
The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on May 24, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 5/24/04

INT-03-008

U.S. Patent Application Publication US 2002/0109634 A1 to Aisenbrey, "Low Cost Antennas Using Conductive Plastics or Conductive Composites," discusses low cost antennas formed of conductive loaded resin-based materials.

U.S. Patent Application INT-01-002_CIP, filed 12/04/02, Serial No. 10/309,429, assigned to the same assignee, "Low Cost Antennas Using Conductive Plastics or Conductive Composites," discusses antennas formed of conductive loaded resin-based materials comprising micron conductive powders or micron conductive fibers.

U.S. Patent 6,565,772 to Schneck, "Conductive Resin Composition," teaches a conductive resin comprising resin, a cure accelerant, and a conductive particulate.

U.S. Patent 6,451,418 to Tobita, "Heat Conductive Resin Substrate and Semiconductor Package," describes a substrate or a chip package constructed from a heat conductive resin material.

U.S. Patent 6,284,817 to Cross et al., "Conductive, Resin-Based Compositions," discloses a conductive resin-based material including aluminum oxide and zinc oxide particles.

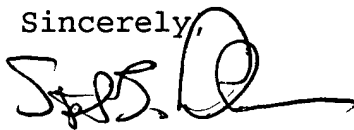
INT-03-008

U.S. Patent 6,597,063 to Shimizu et al., "Package for Semiconductor Power Device and Method for Assembling the Same," discloses a package for a semiconductor power device.

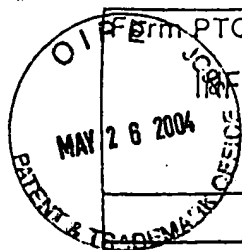
U.S. Patent Application Publication US 2003/0183379 A1 to Krassowski et al., "Optimized Heat Sink Using High Thermal Conducting Base and Low Thermal Conducting FINs," teaches a composite heat sink comprising a graphite base and conductive plastic fins.

UK Patent Application GB 2 377 449 A to Michael Patrick Sayers, "Electrically Conductive Polymer Composition," discusses electrically conductive compositions, and to their use to prevent electrostatic discharges and to earth electrical devices.

Sincerely,

A handwritten signature in black ink, appearing to read 'S. B. Ackerman', with a long horizontal flourish extending to the right.

Stephen B. Ackerman,
Reg. No. 37761



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Form PTO-1449

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)

INT-03-008

Application Number

10/807,036

Applicant

Thomas Aisenbrey

Filing Date

03/23/04

Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILED DATE IF APPROPRIATE
	6565772	5/20/03	Schneck	252	511	9/25/01
	6451418	9/17/02	Tobita	428	297.4	3/22/00
	6284817	9/4/01	Cross et al.	523	220	2/29/00
	6597063	7/22/03	Shimizu et al.	257	687	4/4/00

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
	GB 2377449A	1/15/03	UK Patent App.	08K	3/08 7/06		

OTHER DOCUMENTS (Including Author, Title, Date, Port/next Pages, Etc.)

-	US Patent App. INT-01-002-CIP, Ser# 10/309,429, filed 12/4/02, assigned to the same assignee, "Low Cost Antennas Using Conductive Plastics or Conductive Composites".
-	US Patent App. Pub. US 2002/0109634 A1, to Aisenbrey, Pub. Date - 8/15/02, Filed 2/14/02, US Cl. 343/700 ms.
-	US Patent App. Pub. US 2003/0183379 A1, to Krassowski et al., Pub Date 10/2/03, Filed 3/29/02, US Cl. 165/185.

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.